CLAIMS

1. A cleaning device comprising a fiber bundle composed of a large number of fibers bonded to a base material sheet by an adhesive.

2. The cleaning device according to Claim 1, characterized in that a bristle-like-member-less portion of a brush sheet having a plurality of bristle-like members is integrally bonded to the fiber bundle and the base material sheet by an adhesive.

3. The cleaning device according to Claim 1, characterized in that the fiber bundle is a filament bundling body equipped with a bundling portion connecting filaments aligned in a fiber direction to each other.

4. The cleaning device according to Claim 2, characterized in that the base material sheet has a plurality of strips.

5. The cleaning device according to Claim 3, characterized in that the base material sheet has a plurality of strips.

6. The cleaning device according to Claim 2, characterized in that the fiber bundle is formed by stacking together a fiber bundle composed of fibers of a low degree of fineness and a fiber bundle composed of fibers of a high degree of fineness.

7. The cleaning device according to Claim 3, characterized in that the fiber bundle is formed by stacking together a fiber bundle composed of fibers of a low degree of fineness and a fiber bundle composed of fibers of a high degree of fineness.

8. The cleaning device according to Claim 2, characterized in that the fibers constituting the fiber bundle and the brush sheet are formed of materials different from each other.

9. The cleaning device according to Claim 2, characterized in that the fiber bundle is provided between the base material sheet and the brush sheet.

10. The cleaning device according to Claim 2, characterized in that the bristle-like members of the brush sheet have a width larger than a diameter of the fibers forming the fiber bundle.

11. The cleaning device according to Claim 3, characterized in that the bundling portion is provided linearly in a direction crossing the filaments.

12. The cleaning device according to Claim 3, characterized in that the bonding portion of the filament bundling body and the base material sheet is provided linearly.

13. The cleaning device according to Claim 3, characterized in that the bonding portion of the filament bundling body and the base material sheet is provided in a form of a plurality of spots.

14. The cleaning device according to Claim 3, characterized in that the filament bundling body is bonded to the base material sheet atby the bonding portion of a predetermined width located at a substantially central position with respect to the fiber direction.

15. The cleaning device according to Claim 1, characterized

in that the adhesive is a hot melt type adhesive.

16. The cleaning device according to Claim 1, characterized in that the adhesive contains a coloring agent.

17. The cleaning device according to Claim 1, characterized in that the base material sheet has a handle mounting portion.

18. The cleaning device according to Claim 1, characterized in that the fiber bundle is provided on both upper and lower sides of the base material sheet.

19. A process for producing a cleaning device, comprising:

aligning a large number of filaments with fusibility in fiber direction;

fusing together substantially central portions of the filaments by fusing means to form a filament bundling body;

applying an adhesive to a position corresponding to of a bonding portion between the filament bundling body and a base material sheet;

stacking together the filament bundling body and the base material sheet; and

bonding together the filament bundling body and the base material sheet at the position of the bonding portion.

20. A process for producing a cleaning device, comprising:

aligning a large number of filaments with fusibility in fiber direction;

fusing together substantially central portions of the filaments by fusing means to form a filament bundling body;

applying a hot melt type adhesive to a position corresponding to of a bonding portion between the filament bundling body and a base material sheet;

stacking together the filament bundling body and the base material sheet;

heating the filament bundling body and the base material sheet to a temperature not lower than a melting temperature of the hot melt type adhesive by a press heater and pressurizing the filament bundling body and the base material sheet; and

heating the position of the bonding portion to a temperature not lower than a fusion temperature of the filaments by a hot cutter and pressurizing the position of the bonding portion to bond together the filament bundling body and the base material sheet at the position of the bonding portion.